

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

Appl. No. : 10/809,182 Confirmation No. 6820  
Applicant(s) : UMENO, Kuniharu et al.  
Filed : 03/25/2004  
TC/A.U. : 1712  
Examiner : Robert E. Sellers  
Title : Resin Composition for Encapsulating Semiconductor Chip and  
Semiconductor Device Therewith  
  
Docket No. : 033036.076  
Customer No. : 25461

**MAIL STOP AF**  
Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450  
Sir:

**AMENDMENT UNDER 37 C.F.R. § 1.116**

This is in response to the Final Office Action of November 7, 2006. Please amend the  
above-identified application as follows:

**Amendments to the specification are reflected beginning on page 2.**

**Amendments to the Claims are reflected in the listing of claims which begins on page 4  
of this paper.**

**Remarks/Arguments begin on page 9 of this paper.**

**Attachments:**

**New Declaration – 4 pgs.**

OK TO ENTER  
3-7-07  
BH  
~~ENTER~~  
1/12/2007